

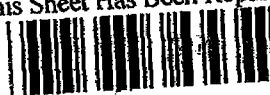
METHOD FOR MAKING A CIRCUITIZED SUBSTRATE USING
TWO DIFFERENT METALLIZATION PROCESSES

Abstract

A process for making a circuitized substrate is defined wherein the substrate is treated with two different, e.g., additive and subtractive, metallization processes. The process is thus able to effectively produce substrate having a first layer (61) and a second layer (81) including conductive features, e.g., high density circuit lines and chip heat-sinking pads, of two different degrees of resolution in a cost effective and expeditious manner. The resulting product is also defined.

Figure 14

This Sheet Has Been Replaced



THIS SHEET HAS BEEN
REPLACED